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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Masahiro Nakano, et al.

Serial No.: 10/813,393

Group Art Unit: 2818

Filing Date: March 31, 2004

Examiner: Tran, Long K.

For: PACKAGING SUBSTRATE AND MANUFACTURING METHOD THEREOF,  
INTEGRATED CIRCUIT DEVICE AND MANUFACTURING METHOD THEREOF,  
AND SAW DEVICE

Honorable Commissioner of Patents  
Alexandria, Virginia 22313-1450

**PRIOR ART SUBMISSION**

Sir:

For the possible benefit of anyone subsequently evaluating the scope and/or validity of the above patent, it is respectfully requested that the following references be placed in the file wrapper.

1. US-5,241,133 A, Mullen, et al.
2. US-5,991,989 A, Onishi, et al.
3. US-5,939,772 A, Hurst, et al.
4. US-6,518,501 B1, Kawahara et al.

Please charge any deficiencies in fees and credit any overpayment of fees to Attorney's Deposit Account No. 50-0481.

Respectfully submitted,

Phillip E. Miller, Esq.  
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Date: 11/16/05

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